

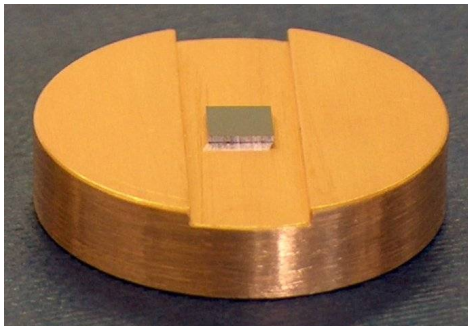
Soldered SAM data sheet SAM-λ-A-τ-4.0-25.4s-c or 4.0-25.4s-e

GaAs chip area	standard:	4.0 mm x 4.0 mm
	optional:	other dimensions on request
Chip thickness	standard:	450 μm
Front side protection		the SAM is protected with a dielectric front layer.

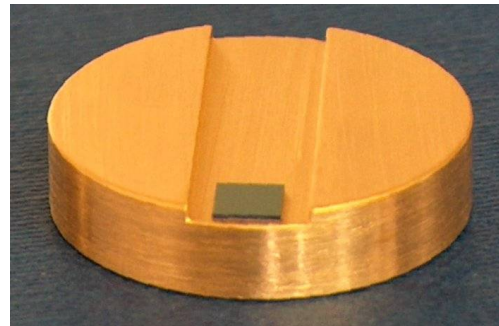
The SAM chip is soldered on a gold plated Cu-cylinder with 25.4 mm \varnothing using a Sn/Bi solder. The solder ensures a low thermal resistance between the SAM and the heat sink.

- The **standard** position of the SAM is at the center of the mount $\rightarrow x = 4.0-25.4s-c$.
- **Optional** the SAM can be mounted at the edge of the mount without extra charges.
 $\rightarrow x = 4.0-25.4s-e$.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, $\varnothing = 25.4 \text{ mm}$
 $l = 6.0 \text{ mm}$

